

Amendments to the Specification:

Please amend the paragraph on page 2, line 23 -- page 3, line 1 as follows:

The present invention has been ~~made~~made taking the problems as described above into consideration, an object of which is to provide a heat spreader module which makes it possible to suppress a base from deformation even when a hard solder material is used as a joining material and which does not ~~lowers~~lower the coefficient of thermal conductivity.